

Jakob Schober

List of Publications by Year in descending order

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4
papers

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3311381
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docs citations

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citing authors

#	ARTICLE	IF	CITATIONS
1	Reliability Study of Miniaturized Surface Acoustic Wave RF-Filters With Copper Pillar Bump Interconnections. IEEE Access, 2021, 9, 140581-140589.	4.2	1
2	Thick Film Photoresist Process for Copper Pillar Bumps on Surface Acoustic Wave - Wafer Level Packages. , 2020, , .		5
3	Reliability Study of Copper Pillar Bump Interconnects for Acoustic Wave - Wafer Level Package. , 2020, , .		0
4	Rotate-to-bend setup for fatigue bending tests on inkjet-printed silver lines. Flexible and Printed Electronics, 2018, 3, 035005.	2.7	2